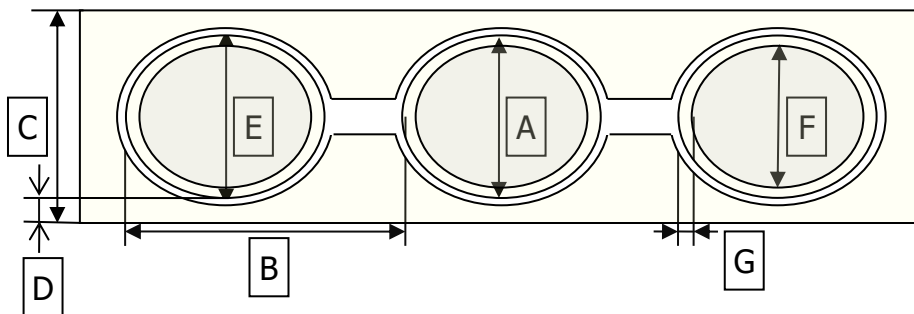


1. MODEL : AWP3 series

2. FEATURE

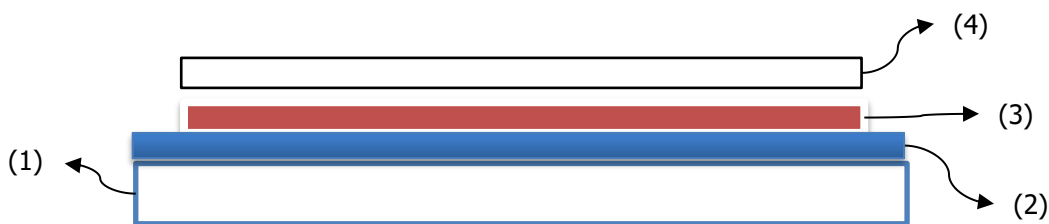
- Functional material for both dicing and die bonding
- Thermal curing type, high adhesive strength
- Strong resistance against humid circumstance
- Low modulus at high temperature

3. PRE-CUT STYLE



| | A | B | C | D | E | F | G |
|---------|-------|-----------|-------|------|-------|-------|------|
| 8 inch | 260±1 | 279.8±1.5 | 290±2 | 15±2 | 267±1 | 220±1 | 20±2 |
| 12 inch | 370±1 | 378.5±1.5 | 390±2 | 10±2 | 377±1 | 320±1 | 25±2 |

4. COMPOSITION



WBL

- (1) Base Film (80μm)
- (2) Adhesive Layer (30μm)
- (3) DAF (10~30μm)
- (4) Protective Film (38μm)

5. Expiration time

12 months after production (-5 ~ 5°C)

4 weeks after opening

6. SPECIFICATION

| ITEM | | AWP3-20 | |
|------------|---|--|-------------------------|
| Appearance | Tape color | milky white | |
| | Tape thickness | 173 μ m | |
| | Base film | Polyolefin / 80 μ m | |
| | DAF | 20 μ m | |
| | Adhesive layer | 30 μ m | |
| | Protective film | PET / 38 μ m | |
| Properties | Peel strength of Dicing Film (SUS) | 0.26 N/25mm ¹⁾ | |
| | Peel strength of DCF/DAF | 0.27 N/25mm | |
| | Die shear strength (2 \times 2mm, Si die on glass substrate) @ 260 $^{\circ}$ C | 7.6 N/mm ² | |
| | Wafer mounting temperature | 60-80 $^{\circ}$ C | |
| | Cure starting temperature | 120 $^{\circ}$ C | |
| | Die bonding temperature | 110-130 $^{\circ}$ C | |
| | Curing condition | 1 hour @180 $^{\circ}$ C (ramp-up 30min) | |
| | CTE | below Tg | 186.0 ppm/ $^{\circ}$ C |
| | | above Tg | 194.4ppm/ $^{\circ}$ C |
| | Tg | 197.1 $^{\circ}$ C | |
| | Elastic modulus | 12.8 MPa (at 250 $^{\circ}$ C) | |
| | Enthalpy | 58.9 J/g | |
| | Water absorption (85 $^{\circ}$ C/85RH%/48Hrs) | 0.9 % | |
| | RoHS | Nothing | |

cf) These values are measured values and not guaranteed value

7. Remark

* 1) Peel strength on SUS#304

** JIS Z 0237 / KS A 1107

Peeling speed : 300mm/min

Peeling angle : 180deg.